



IPW

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

MATTHIAS BONKA β
AXEL PREUSSE
MARKUS NOPPER

Serial No.: 10/629,106

Filed: July 29, 2003

For: METHOD OF PLATING A
SEMICONDUCTOR STRUCTURE

Examiner: Luan V. Van

Group Art Unit: 1753

Att'y Docket: 2000.108300/DE0340

Customer No.: 23720

RESPONSE TO OFFICE ACTION DATED SEPTEMBER 7, 2005

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

CERTIFICATE OF MAILING
37 C.F.R 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on the date below:

November 2, 2005

Date



Signature

This paper is submitted in response to the Office Action dated September 7, 2005, for which the three-month date for response is December 7, 2005.

No fees are believed to be due in connection with the present paper. However, should any fees be required under 37 C.F.R. §§ 1.16 to 1.21, the Director is authorized to deduct such fees from the Advanced Micro Devices, Inc. Deposit Account No. 01-0365/DE0340.¹

Reconsideration of the application in view of the following amendments and remarks is respectfully requested.

¹ In the event the monies in that account are insufficient, the Director is authorized to withdraw funds from Williams, Morgan & Amerson, P.C. Deposit Account No. 50-0786/2000.108300.